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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Active
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	16
Number of Macrocells	256
Number of Gates	-
Number of I/O	64
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4256v-5tn100c

Table 5. Product Term Expansion Capability

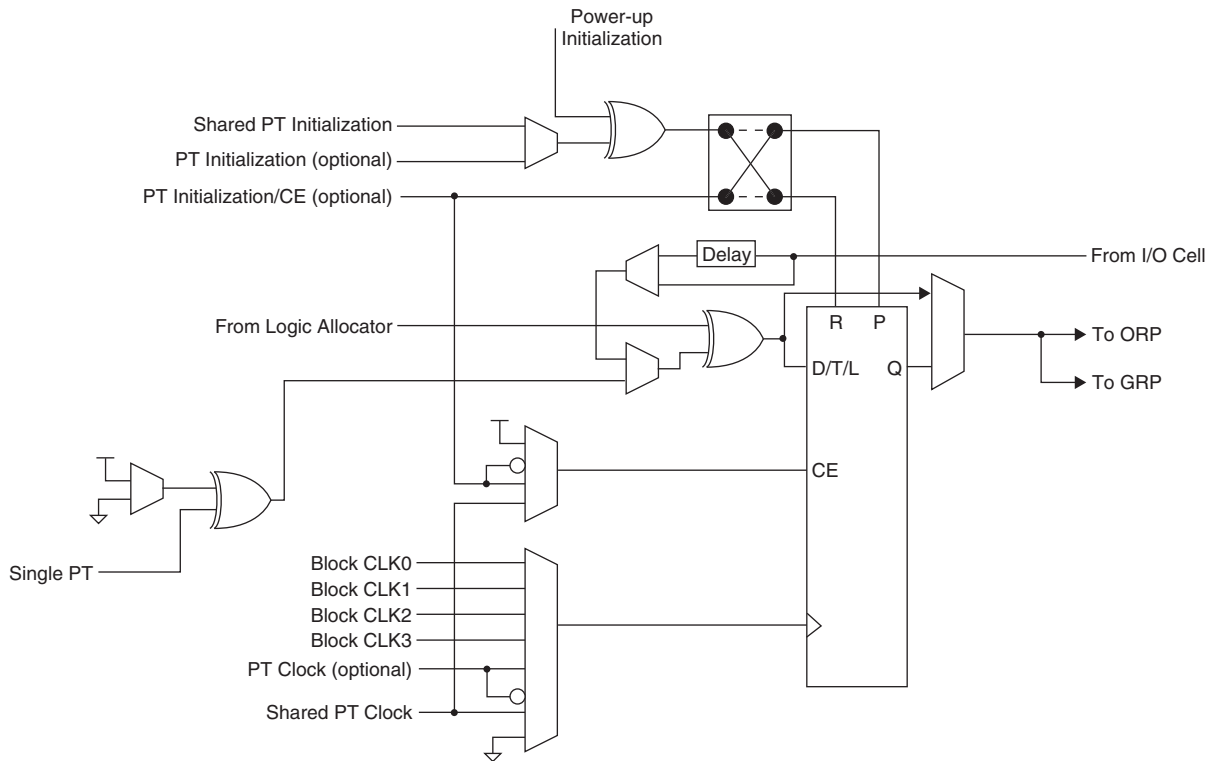
Expansion Chains	Macrocells Associated with Expansion Chain (with Wrap Around)	Max PT/Macrocell
Chain-0	M0 M4 M8 M12 M0	75
Chain-1	M1 M5 M9 M13 M1	80
Chain-2	M2 M6 M10 M14 M2	75
Chain-3	M3 M7 M11 M15 M3	70

Every time the super cluster allocator is used, there is an incremental delay of t_{EXP} . When the super cluster allocator is used, all destinations other than the one being steered to, are given the value of ground (i.e., if the super cluster is steered to M (n+4), then M (n) is ground).

Macrocell

The 16 macrocells in the GLB are driven by the 16 outputs from the logic allocator. Each macrocell contains a programmable XOR gate, a programmable register/latch, along with routing for the logic and control functions. Figure 5 shows a graphical representation of the macrocell. The macrocells feed the ORP and GRP. A direct input from the I/O cell allows designers to use the macrocell to construct high-speed input registers. A programmable delay in this path allows designers to choose between the fastest possible set-up time and zero hold time.

Figure 5. Macrocell



Enhanced Clock Multiplexer

The clock input to the flip-flop can select any of the four block clocks along with the shared PT clock, and true and complement forms of the optional individual term clock. An 8:1 multiplexer structure is used to select the clock. The eight sources for the clock multiplexer are as follows:

- Block CLK0
- Block CLK1

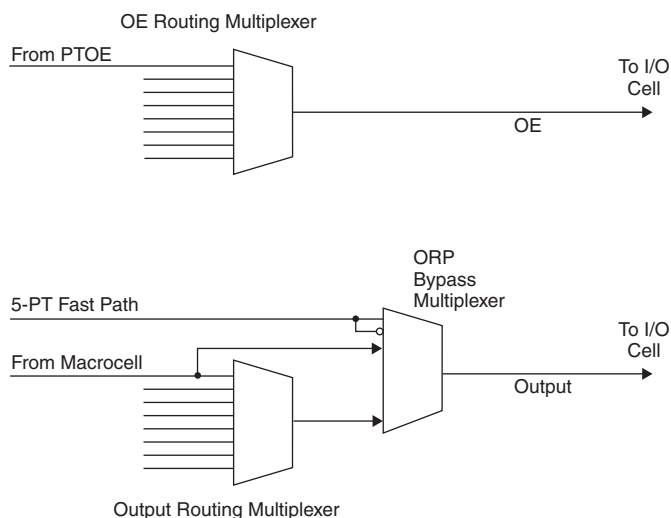
Output Routing Pool (ORP)

The Output Routing Pool allows macrocell outputs to be connected to any of several I/O cells within an I/O block. This provides greater flexibility in determining the pinout and allows design changes to occur without affecting the pinout. The output routing pool also provides a parallel capability for routing macrocell-level OE product terms. This allows the OE product term to follow the macrocell output as it is switched between I/O cells. Additionally, the output routing pool allows the macrocell output or true and complement forms of the 5-PT bypass signal to bypass the output routing multiplexers and feed the I/O cell directly. The enhanced ORP of the ispMACH 4000 family consists of the following elements:

- Output Routing Multiplexers
- OE Routing Multiplexers
- Output Routing Pool Bypass Multiplexers

Figure 7 shows the structure of the ORP from the I/O cell perspective. This is referred to as an ORP slice. Each ORP has as many ORP slices as there are I/O cells in the corresponding I/O block.

Figure 7. ORP Slice



Output Routing Multiplexers

The details of connections between the macrocells and the I/O cells vary across devices and within a device dependent on the maximum number of I/Os available. Tables 5-9 provide the connection details.

Table 6. ORP Combinations for I/O Blocks with 8 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M2, M3, M4, M5, M6, M7, M8, M9
I/O 2	M4, M5, M6, M7, M8, M9, M10, M11
I/O 3	M6, M7, M8, M9, M10, M11, M12, M13
I/O 4	M8, M9, M10, M11, M12, M13, M14, M15
I/O 5	M10, M11, M12, M13, M14, M15, M0, M1
I/O 6	M12, M13, M14, M15, M0, M1, M2, M3
I/O 7	M14, M15, M0, M1, M2, M3, M4, M5

- LVTTTL
- LVC MOS 3.3
- LVC MOS 2.5
- LVC MOS 1.8
- 3.3V PCI Compatible

All of the I/Os and dedicated inputs have the capability to provide a bus-keeper latch, Pull-up Resistor or Pull-down Resistor. A fourth option is to provide none of these. The selection is done on a global basis. The default in both hardware and software is such that when the device is erased or if the user does not specify, the input structure is configured to be a Pull-up Resistor.

Each ispMACH 4000 device I/O has an individually programmable output slew rate control bit. Each output can be individually configured for fast slew or slow slew. The typical edge rate difference between fast and slow slew setting is 20%. For high-speed designs with long, unterminated traces, the slow-slew rate will introduce fewer reflections, less noise and keep ground bounce to a minimum. For designs with short traces or well terminated lines, the fast slew rate can be used to achieve the highest speed.

Global OE Generation

Most ispMACH 4000 family devices have a 4-bit wide Global OE Bus, except the ispMACH 4032 device that has a 2-bit wide Global OE Bus. This bus is derived from a 4-bit internal global OE PT bus and two dual purpose I/O or GOE pins. Each signal that drives the bus can optionally be inverted.

Each GLB has a block-level OE PT that connects to all bits of the Global OE PT bus with four fuses. Hence, for a 256-macrocell device (with 16 blocks), each line of the bus is driven from 16 OE product terms. Figures 9 and 10 show a graphical representation of the global OE generation.

Figure 9. Global OE Generation for All Devices Except ispMACH 4032



I/O Recommended Operating Conditions

Standard	V_{CCO} (V) ¹	
	Min.	Max.
LVTTTL	3.0	3.6
LVC MOS 3.3	3.0	3.6
Extended LVC MOS 3.3 ²	2.7	3.6
LVC MOS 2.5	2.3	2.7
LVC MOS 1.8	1.65	1.95
PCI 3.3	3.0	3.6

1. Typical values for V_{CCO} are the average of the min. and max. values.

2. ispMACH 4000Z only.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$I_{IL}, I_{IH}^{1,4}$	Input Leakage Current (ispMACH 4000Z)	$0 \leq V_{IN} < V_{CCO}$	—	0.5	1	μA
I_{IH}^1	Input High Leakage Current (ispMACH 4000Z)	$V_{CCO} < V_{IN} \leq 5.5V$	—	—	10	μA
I_{IL}, I_{IH}^1	Input Leakage Current (ispMACH 4000V/B/C)	$0 \leq V_{IN} \leq 3.6V, T_j = 105^\circ C$	—	—	10	μA
		$0 \leq V_{IN} \leq 3.6V, T_j = 130^\circ C$	—	—	15	μA
$I_{IH}^{1,2}$	Input High Leakage Current (ispMACH 4000V/B/C)	$3.6V < V_{IN} \leq 5.5V, T_j = 105^\circ C$ $3.0V \leq V_{CCO} \leq 3.6V$	—	—	20	μA
		$3.6V < V_{IN} \leq 5.5V, T_j = 130^\circ C$ $3.0V \leq V_{CCO} \leq 3.6V$	—	—	50	μA
I_{PU}	I/O Weak Pull-up Resistor Current (ispMACH 4000Z)	$0 \leq V_{IN} \leq 0.7V_{CCO}$	-30	—	-150	μA
	I/O Weak Pull-up Resistor Current (ispMACH 4000V/B/C)	$0 \leq V_{IN} \leq 0.7V_{CCO}$	-30	—	-200	μA
I_{PD}	I/O Weak Pull-down Resistor Current	$V_{IL} (MAX) \leq V_{IN} \leq V_{IH} (MIN)$	30	—	150	μA
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL} (MAX)$	30	—	—	μA
I_{BHHS}	Bus Hold High Sustaining Current	$V_{IN} = 0.7 V_{CCO}$	-30	—	—	μA
I_{BHLO}	Bus Hold Low Overdrive Current	$0V \leq V_{IN} \leq V_{BHT}$	—	—	150	μA
I_{BHHO}	Bus Hold High Overdrive Current	$V_{BHT} \leq V_{IN} \leq V_{CCO}$	—	—	-150	μA
V_{BHT}	Bus Hold Trip Points	—	$V_{CCO} * 0.35$	—	$V_{CCO} * 0.65$	V
C_1	I/O Capacitance ³	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	8	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0$ to $V_{IH} (MAX)$	—		—	
C_2	Clock Capacitance ³	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	6	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0$ to $V_{IH} (MAX)$	—		—	
C_3	Global Input Capacitance ³	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	6	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0$ to $V_{IH} (MAX)$	—		—	

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tristated. It is not measured with the output driver active. Bus maintenance circuits are disabled.

2. 5V tolerant inputs and I/O should only be placed in banks where $3.0V \leq V_{CCO} \leq 3.6V$.

3. $T_A = 25^\circ C, f = 1.0MHz$

4. I_{IH} excursions of up to 1.5 μA maximum per pin above the spec limit may be observed for certain voltage conditions on no more than 10% of the device's I/O pins.

I/O DC Electrical Characteristics

Over Recommended Operating Conditions

Standard	V_{IL}		V_{IH}		V_{OL} Max (V)	V_{OH} Min (V)	I_{OL}^1 (mA)	I_{OH}^1 (mA)
	Min (V)	Max (V)	Min (V)	Max (V)				
LVTTTL	-0.3	0.80	2.0	5.5	0.40	$V_{CCO} - 0.40$	8.0	-4.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 3.3	-0.3	0.80	2.0	5.5	0.40	$V_{CCO} - 0.40$	8.0	-4.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 2.5	-0.3	0.70	1.70	3.6	0.40	$V_{CCO} - 0.40$	8.0	-4.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 1.8 (4000V/B)	-0.3	0.63	1.17	3.6	0.40	$V_{CCO} - 0.45$	2.0	-2.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 1.8 (4000C/Z)	-0.3	$0.35 * V_{CC}$	$0.65 * V_{CC}$	3.6	0.40	$V_{CCO} - 0.45$	2.0	-2.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
PCI 3.3 (4000V/B)	-0.3	1.08	1.5	5.5	$0.1 V_{CCO}$	$0.9 V_{CCO}$	1.5	-0.5
PCI 3.3 (4000C/Z)	-0.3	$0.3 * 3.3 * (V_{CC} / 1.8)$	$0.5 * 3.3 * (V_{CC} / 1.8)$	5.5	$0.1 V_{CCO}$	$0.9 V_{CCO}$	1.5	-0.5

1. The average DC current drawn by I/Os between adjacent bank GND connections, or between the last GND in an I/O bank and the end of the I/O bank, as shown in the logic signals connection table, shall not exceed $n * 8mA$. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

ispMACH 4000V/B/C External Switching Characteristics (Cont.)

Over Recommended Operating Conditions

Parameter	Description ^{1, 2, 3}	-5		-75		-10		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{PD}	5-PT bypass combinatorial propagation delay	—	5.0	—	7.5	—	10.0	ns
t _{PD_MC}	20-PT combinatorial propagation delay through macrocell	—	5.5	—	8.0	—	10.5	ns
t _S	GLB register setup time before clock	3.0	—	4.5	—	5.5	—	ns
t _{ST}	GLB register setup time before clock with T-type register	3.2	—	4.7	—	5.5	—	ns
t _{SIR}	GLB register setup time before clock, input register path	1.2	—	1.7	—	1.7	—	ns
t _{SIRZ}	GLB register setup time before clock with zero hold	2.2	—	2.7	—	2.7	—	ns
t _H	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
t _{HT}	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
t _{HIR}	GLB register hold time after clock, input register path	1.0	—	1.0	—	1.0	—	ns
t _{HIRZ}	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
t _{CO}	GLB register clock-to-output delay	—	3.4	—	4.5	—	6.0	ns
t _R	External reset pin to output delay	—	6.3	—	9.0	—	10.5	ns
t _{RW}	External reset pulse duration	2.0	—	4.0	—	4.0	—	ns
t _{P_{TOE/DIS}}	Input to output local product term output enable/disable	—	7.0	—	9.0	—	10.5	ns
t _{G_{P_{TOE/DIS}}}	Input to output global product term output enable/disable	—	9.0	—	10.3	—	12.0	ns
t _{G_{OE/DIS}}	Global OE input to output enable/disable	—	5.0	—	7.0	—	8.0	ns
t _{CW}	Global clock width, high or low	2.2	—	2.8	—	4.0	—	ns
t _{GW}	Global gate width low (for low transparent) or high (for high transparent)	2.2	—	2.8	—	4.0	—	ns
t _{WIR}	Input register clock width, high or low	2.2	—	2.8	—	4.0	—	ns
f _{MAX} ⁴	Clock frequency with internal feedback	—	227	—	168	—	125	MHz
f _{MAX} (Ext.)	Clock frequency with external feedback, [1/ (t _S + t _{CO})]	—	156	—	111	—	86	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards. Timing v.3.2
2. Measured using standard switching circuit, assuming GRP loading of 1 and 1 output switching.
3. Pulse widths and clock widths less than minimum will cause unknown behavior.
4. Standard 16-bit counter using GRP feedback.

ispMACH 4000V/B/C Internal Timing Parameters (Cont.)**Over Recommended Operating Conditions**

Parameter	Description	-2.5		-2.7		-3		-3.5		Units
t_{PDLi}	Propagation Delay through Transparent Latch to Output/Feedback MUX	—	0.25	—	0.25	—	0.25	—	0.25	ns
t_{SRi}	Asynchronous Reset or Set to Output/Feedback MUX Delay	0.28	—	0.28	—	0.28	—	0.28	—	ns
t_{SRR}	Asynchronous Reset or Set Recovery Time	1.67	—	1.67	—	1.67	—	1.67	—	ns
Control Delays										
t_{BCLK}	GLB PT Clock Delay	—	1.12	—	1.12	—	1.12	—	1.12	ns
t_{PTCLK}	Macrocell PT Clock Delay	—	0.87	—	0.87	—	0.87	—	0.87	ns
t_{BSR}	Block PT Set/Reset Delay	—	1.83	—	1.83	—	1.83	—	1.83	ns
t_{PTSR}	Macrocell PT Set/Reset Delay	—	1.11	—	1.41	—	1.51	—	1.61	ns
t_{GPtoE}	Global PT OE Delay	—	2.83	—	4.13	—	5.33	—	5.33	ns
t_{PtoE}	Macrocell PT OE Delay	—	1.83	—	2.13	—	2.33	—	2.83	ns

Timing v.3.2

Note: Internal Timing Parameters are not tested and are for reference only. Refer to the Timing Model in this data sheet for further details.

ispMACH 4000V/B/C Internal Timing Parameters

Over Recommended Operating Conditions

Parameter	Description	-5		-75		-10		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
In/Out Delays								
t _{IN}	Input Buffer Delay	—	0.95	—	1.50	—	2.00	ns
t _{GOE}	Global OE Pin Delay	—	4.04	—	6.04	—	7.04	ns
t _{GCLK_IN}	Global Clock Input Buffer Delay	—	1.83	—	2.28	—	3.28	ns
t _{BUF}	Delay through Output Buffer	—	1.00	—	1.50	—	1.50	ns
t _{EN}	Output Enable Time	—	0.96	—	0.96	—	0.96	ns
t _{DIS}	Output Disable Time	—	0.96	—	0.96	—	0.96	ns
Routing/GLB Delays								
t _{ROUTE}	Delay through GRP	—	1.51	—	2.26	—	3.26	ns
t _{MCELL}	Macrocell Delay	—	1.05	—	1.45	—	1.95	ns
t _{INREG}	Input Buffer to Macrocell Register Delay	—	0.56	—	0.96	—	1.46	ns
t _{FBK}	Internal Feedback Delay	—	0.00	—	0.00	—	0.00	ns
t _{PDb}	5-PT Bypass Propagation Delay	—	1.54	—	2.24	—	3.24	ns
t _{PDi}	Macrocell Propagation Delay	—	0.94	—	1.24	—	1.74	ns
Register/Latch Delays								
t _S	D-Register Setup Time (Global Clock)	1.32	—	1.57	—	1.57	—	ns
t _{S_PT}	D-Register Setup Time (Product Term Clock)	1.32	—	1.32	—	1.32	—	ns
t _{ST}	T-Register Setup Time (Global Clock)	1.52	—	1.77	—	1.77	—	ns
t _{ST_PT}	T-Register Setup Time (Product Term Clock)	1.32	—	1.32	—	1.32	—	ns
t _H	D-Register Hold Time	1.68	—	2.93	—	3.93	—	ns
t _{HT}	T-Register Hold Time	1.68	—	2.93	—	3.93	—	ns
t _{SIR}	D-Input Register Setup Time (Global Clock)	1.52	—	1.57	—	1.57	—	ns
t _{SIR_PT}	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45	—	ns
t _{HIR}	D-Input Register Hold Time (Global Clock)	0.68	—	1.18	—	1.18	—	ns
t _{HIR_PT}	D-Input Register Hold Time (Product Term Clock)	0.68	—	1.18	—	1.18	—	ns
t _{COi}	Register Clock to Output/Feedback MUX Time	—	0.52	—	0.67	—	1.17	ns
t _{CES}	Clock Enable Setup Time	2.25	—	2.25	—	2.25	—	ns
t _{CEH}	Clock Enable Hold Time	1.88	—	1.88	—	1.88	—	ns
t _{SL}	Latch Setup Time (Global Clock)	1.32	—	1.57	—	1.57	—	ns
t _{SL_PT}	Latch Setup Time (Product Term Clock)	1.32	—	1.32	—	1.32	—	ns
t _{HL}	Latch Hold Time	1.17	—	1.17	—	1.17	—	ns
t _{GOi}	Latch Gate to Output/Feedback MUX Time	—	0.33	—	0.33	—	0.33	ns
t _{PDLi}	Propagation Delay through Transparent Latch to Output/Feedback MUX	—	0.25	—	0.25	—	0.25	ns
t _{SRI}	Asynchronous Reset or Set to Output/Feedback MUX Delay	0.28	—	0.28	—	0.28	—	ns
t _{SRR}	Asynchronous Reset or Set Recovery Time	1.67	—	1.67	—	1.67	—	ns
Control Delays								
t _{BCLK}	GLB PT Clock Delay	—	1.12	—	1.12	—	0.62	ns
t _{PTCLK}	Macrocell PT Clock Delay	—	0.87	—	0.87	—	0.87	ns
t _{BSR}	GLB PT Set/Reset Delay	—	1.83	—	1.83	—	1.83	ns
t _{PTSR}	Macrocell PT Set/Reset Delay	—	2.51	—	3.41	—	3.41	ns

ispMACH 4000Z Internal Timing Parameters (Cont.)

Over Recommended Operating Conditions

Parameter	Description	-35		-37		-42		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{GP} TOE	Global PT OE Delay	—	1.9	—	2.35	—	2.60	ns
t _P TOE	Macrocell PT OE Delay	—	2.4	—	3.35	—	2.60	ns

Note: Internal Timing Parameters are not tested and are for reference only. Refer to the timing model in this data sheet for further details.

Timing v.2.2

ispMACH 4000Z Internal Timing Parameters (Cont.)

Over Recommended Operating Conditions

Parameter	Description	-45		-5		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
In/Out Delays								
t _{IN}	Input Buffer Delay	—	0.95	—	1.25	—	1.80	ns
t _{GOE}	Global OE Pin Delay	—	3.00	—	3.50	—	4.30	ns
t _{GCLK_IN}	Global Clock Input Buffer Delay	—	1.95	—	2.05	—	2.15	ns
t _{BUF}	Delay through Output Buffer	—	1.10	—	1.00	—	1.30	ns
t _{EN}	Output Enable Time	—	2.50	—	2.50	—	2.70	ns
t _{DIS}	Output Disable Time	—	2.50	—	2.50	—	2.70	ns
Routing/GLB Delays								
t _{ROUTE}	Delay through GRP	—	2.25	—	2.05	—	2.50	ns
t _{MCELL}	Macrocell Delay	—	0.65	—	0.65	—	1.00	ns
t _{INREG}	Input Buffer to Macrocell Register Delay	—	1.00	—	1.00	—	1.00	ns
t _{FBK}	Internal Feedback Delay	—	0.35	—	0.05	—	0.05	ns
t _{PDb}	5-PT Bypass Propagation Delay	—	0.20	—	0.70	—	1.90	ns
t _{PDi}	Macrocell Propagation Delay	—	0.45	—	0.65	—	1.00	ns
Register/Latch Delays								
t _S	D-Register Setup Time (Global Clock)	1.00	—	1.10	—	1.35	—	ns
t _{S_PT}	D-Register Setup Time (Product Term Clock)	2.10	—	1.90	—	2.45	—	ns
t _{ST}	T-Register Setup Time (Global Clock)	1.20	—	1.30	—	1.55	—	ns
t _{ST_PT}	T-register Setup Time (Product Term Clock)	2.30	—	2.10	—	2.75	—	ns
t _H	D-Register Hold Time	1.90	—	1.90	—	3.15	—	ns
t _{HT}	T-Resister Hold Time	1.90	—	1.90	—	3.15	—	ns
t _{SIR}	D-Input Register Setup Time (Global Clock)	1.30	—	1.10	—	0.75	—	ns
t _{SIR_PT}	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45	—	ns
t _{HIR}	D-Input Register Hold Time (Global Clock)	1.30	—	1.50	—	1.95	—	ns
t _{HIR_PT}	D-Input Register Hold Time (Product Term Clock)	1.00	—	1.00	—	1.18	—	ns
t _{COi}	Register Clock to Output/Feedback MUX Time	—	0.75	—	1.15	—	1.05	ns
t _{CES}	Clock Enable Setup Time	2.00	—	2.00	—	2.00	—	ns
t _{CEH}	Clock Enable Hold Time	0.00	—	0.00	—	0.00	—	ns
t _{SL}	Latch Setup Time (Global Clock)	1.00	—	1.00	—	1.65	—	ns
t _{SL_PT}	Latch Setup Time (Product Term Clock)	2.10	—	1.90	—	2.15	—	ns
t _{HL}	Latch Hold Time	2.00	—	2.00	—	1.17	—	ns
t _{GOi}	Latch Gate to Output/Feedback MUX Time	—	0.33	—	0.33	—	0.33	ns
t _{PDLi}	Propagation Delay through Transparent Latch to Output/Feedback MUX	—	0.25	—	0.25	—	0.25	ns
t _{SRI}	Asynchronous Reset or Set to Output/Feedback MUX Delay	—	0.97	—	0.97	—	0.28	ns
t _{SRR}	Asynchronous Reset or Set Recovery Delay	—	1.80	—	1.80	—	1.67	ns
Control Delays								
t _{BCLK}	GLB PT Clock Delay	—	1.55	—	1.55	—	1.25	ns
t _{PTCLK}	Macrocell PT Clock Delay	—	1.55	—	1.55	—	1.25	ns
t _{BSR}	GLB PT Set/Reset Delay	—	1.83	—	1.83	—	1.83	ns
t _{PTSR}	Macrocell PT Set/Reset Delay	—	1.83	—	1.83	—	2.72	ns
t _{GPTOE}	Global PT OE Delay	—	4.30	—	4.20	—	3.50	ns

ispMACH 4000V/B/C Timing Adders¹ (Cont.)

Adder Type	Base Parameter	Description	-5		-75		-10		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Optional Delay Adders									
t_{INDIO}	t_{INREG}	Input register delay	—	1.00	—	1.00	—	1.00	ns
t_{EXP}	t_{MCELL}	Product term expander delay	—	0.33	—	0.33	—	0.33	ns
t_{ORP}	—	Output routing pool delay	—	0.05	—	0.05	—	0.05	ns
t_{BLA}	t_{ROUTE}	Additional block loading adder	—	0.05	—	0.05	—	0.05	ns
t_{IOI} Input Adjusters									
LVTTTL_in	$t_{IN}, t_{GCLK_IN}, t_{GOE}$	Using LVTTTL standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS33_in	$t_{IN}, t_{GCLK_IN}, t_{GOE}$	Using LVC MOS 3.3 standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS25_in	$t_{IN}, t_{GCLK_IN}, t_{GOE}$	Using LVC MOS 2.5 standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS18_in	$t_{IN}, t_{GCLK_IN}, t_{GOE}$	Using LVC MOS 1.8 standard	—	0.00	—	0.00	—	0.00	ns
PCI_in	$t_{IN}, t_{GCLK_IN}, t_{GOE}$	Using PCI compatible input	—	0.60	—	0.60	—	0.60	ns
t_{IOO} Output Adjusters									
LVTTTL_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	ns
LVC MOS33_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	ns
LVC MOS25_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	ns
LVC MOS18_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	ns
PCI_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	ns
Slow Slew	t_{BUF}, t_{EN}	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVC MOS timing.

Timing v.3.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding use of these adders.

ispMACH 4128V/B/C Logic Signal Connections: 128-Pin TQFP (Cont.)

Pin Number	Bank Number	ispMACH 4128V/B/C	
		GLB/MC/Pad	ORP
19	0	C13	C^10
20	0	C12	C^9
21	0	C10	C^8
22	0	C9	C^7
23	0	C8	C^6
24	0	GND (Bank 0)	-
25	0	C6	C^5
26	0	C5	C^4
27	0	C4	C^3
28	0	C2	C^2
29	0	C0	C^0
30	0	VCCO (Bank 0)	-
31	0	TCK	-
32	0	VCC	-
33	0	GND	-
34	0	D14	D^11
35	0	D13	D^10
36	0	D12	D^9
37	0	D10	D^8
38	0	D9	D^7
39	0	D8	D^6
40	0	GND (Bank 0)	-
41	0	VCCO (Bank 0)	-
42	0	D6	D^5
43	0	D5	D^4
44	0	D4	D^3
45	0	D2	D^2
46	0	D1	D^1
47	0	D0	D^0
48	0	CLK1/I	-
49	1	GND (Bank 1)	-
50	1	CLK2/I	-
51	1	VCC	-
52	1	E0	E^0
53	1	E1	E^1
54	1	E2	E^2
55	1	E4	E^3
56	1	E5	E^4
57	1	E6	E^5
58	1	VCCO (Bank 1)	-
59	1	GND (Bank 1)	-
60	1	E8	E^6
61	1	E9	E^7

ispMACH 4064Z, 4128Z and 4256Z Logic Signal Connections: 132-Ball csBGA (Cont.)

Ball Number	Bank Number	ispMACH 4064Z		ispMACH 4128Z		ispMACH 4256Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
D13	1	D10	D ¹⁰	G4	G ³	N6	N ³
D14	1	D9	D ⁹	G2	G ²	N8	N ⁴
D12	1	D8	D ⁸	G1	G ¹	N10	N ⁵
C14	1	I	-	G0	G ⁰	N12	N ⁶
C13	1	NC	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
B14	-	TDO	-	TDO	-	TDO	-
A14	-	VCC	-	VCC	-	VCC	-
A13	-	GND	-	GND	-	GND	-
B13	1	NC	-	H14	H ¹¹	O12	O ⁶
A12	1	I	-	H13	H ¹⁰	O10	O ⁵
C12	1	D7	D ⁷	H12	H ⁹	O8	O ⁴
B12	1	D6	D ⁶	H10	H ⁸	O6	O ³
A11	1	D5	D ⁵	H9	H ⁷	O4	O ²
C11	1	D4	D ⁴	H8	H ⁶	O2	O ¹
B11	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
A10	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
B10	1	NC	-	H6	H ⁵	P12	P ⁶
C10	1	NC	-	H5	H ⁴	P10	P ⁵
B9	1	D3	D ³	H4	H ³	P8	P ⁴
A9	1	D2	D ²	H2	H ²	P6	P ³
C9	1	D1	D ¹	H1	H ¹	P4	P ²
A8	1	D0/GOE1	D ⁰	H0/GOE1	H ⁰	P2/GOE1	P ¹
B8	1	CLK3/I	-	CLK3/I	-	CLK3/I	-
C8	0	CLK0/I	-	CLK0/I	-	CLK0/I	-
B7	-	VCC	-	VCC	-	VCC	-
A7	0	NC ¹	-	NC ¹	-	I ¹	-
C7	0	A0/GOE0	A ⁰	A0/GOE0	A ⁰	A2/GOE0	A ¹
A6	0	A1	A ¹	A1	A ¹	A4	A ²
B6	0	A2	A ²	A2	A ²	A6	A ³
C6	0	A3	A ³	A4	A ³	A8	A ⁴
B5	0	NC	-	A5	A ⁴	A10	A ⁵
A5	0	NC	-	A6	A ⁵	A12	A ⁶
C5	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
B4	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
A4	0	NC	-	A8	A ⁶	B2	B ¹
C4	0	A4	A ⁴	A9	A ⁷	B4	B ²
A3	0	A5	A ⁵	A10	A ⁸	B6	B ³
B3	0	A6	A ⁶	A12	A ⁹	B8	B ⁴
A2	0	A7	A ⁷	A13	A ¹⁰	B10	B ⁵
A1	0	NC	-	A14	A ¹¹	B12	B ⁶

1. For device migration considerations, these NC pins are input signal pins in ispMACH 4256Z device.

**ispMACH 4256V/B/C/Z, 4384V/B/C, 4512V/B/C, Logic Signal Connections:
176-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4256V/B/C/Z		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
60	0	H8	H ⁴	L8	L ⁴	P8	P ⁴
61	0	H6	H ³	L6	L ³	P6	P ³
62	0	H4	H ²	L4	L ²	P4	P ²
63	0	H2	H ¹	L2	L ¹	P2	P ¹
64	0	H0	H ⁰	L0	L ⁰	P0	P ⁰
65	-	GND	-	GND	-	GND	-
66	0	CLK1/I	-	CLK1/I	-	CLK1/I	-
67	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
68	1	CLK2/I	-	CLK2/I	-	CLK2/I	-
69	-	VCC	-	VCC	-	VCC	-
70	1	I0	I ⁰	M0	M ⁰	AX0	AX ⁰
71	1	I2	I ¹	M2	M ¹	AX2	AX ¹
72	1	I4	I ²	M4	M ²	AX4	AX ²
73	1	I6	I ³	M6	M ³	AX6	AX ³
74	1	I8	I ⁴	M8	M ⁴	AX8	AX ⁴
75	1	I10	I ⁵	M10	M ⁵	AX10	AX ⁵
76	1	I12	I ⁶	M12	M ⁶	AX12	AX ⁶
77	1	I14	I ⁷	M14	M ⁷	AX14	AX ⁷
78	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
79	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
80	1	J0	J ⁰	N0	N ⁰	BX0	BX ⁰
81	1	J2	J ¹	N2	N ¹	BX2	BX ¹
82	1	J4	J ²	N4	N ²	BX4	BX ²
83	1	J6	J ³	N6	N ³	BX6	BX ³
84	1	J8	J ⁴	N8	N ⁴	BX8	BX ⁴
85	1	J10	J ⁵	N10	N ⁵	BX10	BX ⁵
86	1	J12	J ⁶	N12	N ⁶	BX12	BX ⁶
87	1	J14	J ⁷	N14	N ⁷	BX14	BX ⁷
88	-	VCC	-	VCC	-	VCC	-
89	-	NC	-	NC	-	NC	-
90	-	GND	-	GND	-	GND	-
91	-	TMS	-	TMS	-	TMS	-
92	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
93	1	K14	K ⁷	O14	O ⁷	CX14	CX ⁷
94	1	K12	K ⁶	O12	O ⁶	CX12	CX ⁶
95	1	K10	K ⁵	O10	O ⁵	CX10	CX ⁵
96	1	K8	K ⁴	O8	O ⁴	CX8	CX ⁴
97	1	K6	K ³	O6	O ³	CX6	CX ³
98	1	K4	K ²	O4	O ²	CX4	CX ²
99	1	K2	K ¹	O2	O ¹	CX2	CX ¹
100	1	K0	K ⁰	O0	O ⁰	CX0	CX ⁰

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:
256-Ball ftBGA/fpBGA (Cont.)**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
R5	0	NC	-	NC	-	NC	-	L4	L^1
T5	0	NC	-	NC	-	I2	I^1	L8	L^2
R6	0	NC	-	NC	-	I0	I^0	L12	L^3
T6	0	NC	-	H14	H^9	G12	G^6	M8	M^2
N7	0	NC	-	H12	H^8	G14	G^7	M12	M^3
P7	0	H14	H^7	H10	H^7	L14	L^7	P14	P^7
R7	0	H12	H^6	H9	H^6	L12	L^6	P12	P^6
L8	0	H10	H^5	H8	H^5	L10	L^5	P10	P^5
T7	0	H8	H^4	H6	H^4	L8	L^4	P8	P^4
M8	0	H6	H^3	H4	H^3	L6	L^3	P6	P^3
N8	0	H4	H^2	H2	H^2	L4	L^2	P4	P^2
R8	0	H2	H^1	H1	H^1	L2	L^1	P2	P^1
P8	0	H0	H^0	H0	H^0	L0	L^0	P0	P^0
-	-	GND	-	GND	-	GND	-	GND	-
T8	0	CLK1/I	-	CLK1/I	-	CLK1/I	-	CLK1/I	-
-	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
N9	1	CLK2/I	-	CLK2/I	-	CLK2/I	-	CLK2/I	-
-	-	VCC	-	VCC	-	VCC	-	VCC	-
P9	1	I0	I^0	I0	I^0	M0	M^0	AX0	AX^0
R9	1	I2	I^1	I1	I^1	M2	M^1	AX2	AX^1
T9	1	I4	I^2	I2	I^2	M4	M^2	AX4	AX^2
T10	1	I6	I^3	I4	I^3	M6	M^3	AX6	AX^3
R10	1	I8	I^4	I6	I^4	M8	M^4	AX8	AX^4
M9	1	I10	I^5	I8	I^5	M10	M^5	AX10	AX^5
P10	1	I12	I^6	I9	I^6	M12	M^6	AX12	AX^6
L9	1	I14	I^7	I10	I^7	M14	M^7	AX14	AX^7
N10	1	NC	-	I12	I^8	BX14	BX^7	DX0	DX^0
T11	1	NC	-	I14	I^9	BX12	BX^6	DX4	DX^1
R11	1	NC	-	NC	-	P0	P^0	EX0	EX^0
T12	1	NC	-	NC	-	P2	P^1	EX4	EX^1
N12	1	NC	-	NC	-	NC	-	EX8	EX^2
-	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
-	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
R12	1	NC	-	NC	-	NC	-	EX12	EX^3
T13	1	NC	-	J0	J^0	BX10	BX^5	DX8	DX^2
P12	1	NC	-	J1	J^1	BX8	BX^4	DX12	DX^3
M10	1	J0	J^0	J2	J^2	N0	N^0	BX0	BX^0
R13	1	J2	J^1	J4	J^3	N2	N^1	BX2	BX^1
L10	1	J4	J^2	J6	J^4	N4	N^2	BX4	BX^2
T14	1	J6	J^3	J8	J^5	N6	N^3	BX6	BX^3
M11	1	J8	J^4	J9	J^6	N8	N^4	BX8	BX^4

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:
256-Ball ftBGA/fpBGA (Cont.)**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
H15	1	M2	M^1	M1	M^1	DX2	DX^1	JX2	JX^1
H14	1	M4	M^2	M2	M^2	DX4	DX^2	JX4	JX^2
H13	1	M6	M^3	M4	M^3	DX6	DX^3	JX6	JX^3
G16	1	M8	M^4	M6	M^4	DX8	DX^4	JX8	JX^4
H12	1	M10	M^5	M8	M^5	DX10	DX^5	JX10	JX^5
G15	1	M12	M^6	M9	M^6	DX12	DX^6	JX12	JX^6
H11	1	M14	M^7	M10	M^7	DX14	DX^7	JX14	JX^7
F16	1	NC	-	M12	M^8	CX0	CX^0	IX0	IX^0
G13	1	NC	-	M14	M^9	CX2	CX^1	IX4	IX^1
G14	1	NC	-	NC	-	EX14	EX^7	KX0	KX^0
F15	1	NC	-	NC	-	EX12	EX^6	KX2	KX^1
E16	1	NC	-	NC	-	NC	-	KX4	KX^2
-	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
-	1	-	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
E15	1	NC	-	NC	-	NC	-	KX6	KX^3
G12	1	NC	-	NC	-	EX10	EX^5	KX8	KX^4
E13	1	NC	-	NC	-	EX8	EX^4	KX10	KX^5
D16	1	NC	-	N0	N^0	CX4	CX^2	IX8	IX^2
E14	1	NC	-	N1	N^1	CX6	CX^3	IX12	IX^3
G11	1	N0	N^0	N2	N^2	FX0	FX^0	NX0	NX^0
D15	1	N2	N^1	N4	N^3	FX2	FX^1	NX2	NX^1
F11	1	N4	N^2	N6	N^4	FX4	FX^2	NX4	NX^2
C16	1	N6	N^3	N8	N^5	FX6	FX^3	NX6	NX^3
F12	1	N8	N^4	N9	N^6	FX8	FX^4	NX8	NX^4
D14	1	N10	N^5	N10	N^7	FX10	FX^5	NX10	NX^5
C15	1	N12	N^6	N12	N^8	FX12	FX^6	NX12	NX^6
B16	1	N14	N^7	N14	N^9	FX14	FX^7	NX14	NX^7
-	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
C14	-	TDO	-	TDO	-	TDO	-	TDO	-
-	-	VCC	-	VCC	-	VCC	-	VCC	-
-	-	GND	-	GND	-	GND	-	GND	-
-	1	-	-	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
A15	1	NC	-	NC	-	EX6	EX^3	KX12	KX^6
B14	1	NC	-	NC	-	EX4	EX^2	KX14	KX^7
E12	1	O14	O^7	O14	O^9	GX14	GX^7	OX14	OX^7
A14	1	O12	O^6	O12	O^8	GX12	GX^6	OX12	OX^6
C13	1	O10	O^5	O10	O^7	GX10	GX^5	OX10	OX^5
D13	1	O8	O^4	O9	O^6	GX8	GX^4	OX8	OX^4
E11	1	O6	O^3	O8	O^5	GX6	GX^3	OX6	OX^3
B13	1	O4	O^2	O6	O^4	GX4	GX^2	OX4	OX^2
F10	1	O2	O^1	O4	O^3	GX2	GX^1	OX2	OX^1

Ordering Information

Note: ispMACH 4000 devices are all dual marked except the slowest commercial speed grade ispMACH 4000Z devices. For example, the commercial speed grade LC4128C-5T100C is also marked with the industrial grade -75I. The commercial grade is always one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade ispMACH 4000Z devices are marked as commercial grade only.

Conventional Packaging

ispMACH 4000ZC (Zero Power, 1.8V) Commercial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-35M56C	32	1.8	3.5	csBGA	56	32	C
	LC4032ZC-5M56C	32	1.8	5	csBGA	56	32	C
	LC4032ZC-75M56C	32	1.8	7.5	csBGA	56	32	C
	LC4032ZC-35T48C	32	1.8	3.5	TQFP	48	32	C
	LC4032ZC-5T48C	32	1.8	5	TQFP	48	32	C
	LC4032ZC-75T48C	32	1.8	7.5	TQFP	48	32	C
LC4064ZC	LC4064ZC-37M132C	64	1.8	3.7	csBGA	132	64	C
	LC4064ZC-5M132C	64	1.8	5	csBGA	132	64	C
	LC4064ZC-75M132C	64	1.8	7.5	csBGA	132	64	C
	LC4064ZC-37T100C	64	1.8	3.7	TQFP	100	64	C
	LC4064ZC-5T100C	64	1.8	5	TQFP	100	64	C
	LC4064ZC-75T100C	64	1.8	7.5	TQFP	100	64	C
	LC4064ZC-37M56C	64	1.8	3.7	csBGA	56	32	C
	LC4064ZC-5M56C	64	1.8	5	csBGA	56	32	C
	LC4064ZC-75M56C	64	1.8	7.5	csBGA	56	32	C
	LC4064ZC-37T48C	64	1.8	3.7	TQFP	48	32	C
	LC4064ZC-5T48C	64	1.8	5	TQFP	48	32	C
	LC4064ZC-75T48C	64	1.8	7.5	TQFP	48	32	C
LC4128ZC	LC4128ZC-42M132C	128	1.8	4.2	csBGA	132	96	C
	LC4128ZC-75M132C	128	1.8	7.5	csBGA	132	96	C
	LC4128ZC-42T100C	128	1.8	4.2	TQFP	100	64	C
	LC4128ZC-75T100C	128	1.8	7.5	TQFP	100	64	C
LC4256ZC	LC4256ZC-45T176C	256	1.8	4.5	TQFP	176	128	C
	LC4256ZC-75T176C	256	1.8	7.5	TQFP	176	128	C
	LC4256ZC-45M132C	256	1.8	4.5	csBGA	132	96	C
	LC4256ZC-75M132C	256	1.8	7.5	csBGA	132	96	C
	LC4256ZC-45T100C	256	1.8	4.5	TQFP	100	64	C
	LC4256ZC-75T100C	256	1.8	7.5	TQFP	100	64	C

ispMACH 4000ZC (1.8V, Zero Power) Industrial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-5M56I	32	1.8	5	csBGA	56	32	I
	LC4032ZC-75M56I	32	1.8	7.5	csBGA	56	32	I
	LC4032ZC-5T48I	32	1.8	5	TQFP	48	32	I
	LC4032ZC-75T48I	32	1.8	7.5	TQFP	48	32	I

ispMACH 4000C (1.8V) Industrial Devices

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032C	LC4032C-5T48I	32	1.8	5	TQFP	48	32	I
	LC4032C-75T48I	32	1.8	7.5	TQFP	48	32	I
	LC4032C-10T48I	32	1.8	10	TQFP	48	32	I
	LC4032C-5T44I	32	1.8	5	TQFP	44	30	I
	LC4032C-75T44I	32	1.8	7.5	TQFP	44	30	I
	LC4032C-10T44I	32	1.8	10	TQFP	44	30	I
LC4064C	LC4064C-5T100I	64	1.8	5	TQFP	100	64	I
	LC4064C-75T100I	64	1.8	7.5	TQFP	100	64	I
	LC4064C-10T100I	64	1.8	10	TQFP	100	64	I
	LC4064C-5T48I	64	1.8	5	TQFP	48	32	I
	LC4064C-75T48I	64	1.8	7.5	TQFP	48	32	I
	LC4064C-10T48I	64	1.8	10	TQFP	48	32	I
	LC4064C-5T44I	64	1.8	5	TQFP	44	30	I
	LC4064C-75T44I	64	1.8	7.5	TQFP	44	30	I
LC4128C	LC4128C-5T128I	128	1.8	5	TQFP	128	92	I
	LC4128C-75T128I	128	1.8	7.5	TQFP	128	92	I
	LC4128C-10T128I	128	1.8	10	TQFP	128	92	I
	LC4128C-5T100I	128	1.8	5	TQFP	100	64	I
	LC4128C-75T100I	128	1.8	7.5	TQFP	100	64	I
	LC4128C-10T100I	128	1.8	10	TQFP	100	64	I
LC4256C	LC4256C-5FT256AI	256	1.8	5	ftBGA	256	128	I
	LC4256C-75FT256AI	256	1.8	7.5	ftBGA	256	128	I
	LC4256C-10FT256AI	256	1.8	10	ftBGA	256	128	I
	LC4256C-5FT256BI	256	1.8	5	ftBGA	256	160	I
	LC4256C-75FT256BI	256	1.8	7.5	ftBGA	256	160	I
	LC4256C-10FT256BI	256	1.8	10	ftBGA	256	160	I
	LC4256C-5F256AI ¹	256	1.8	5	fpBGA	256	128	I
	LC4256C-75F256AI ¹	256	1.8	7.5	fpBGA	256	128	I
	LC4256C-10F256AI ¹	256	1.8	10	fpBGA	256	128	I
	LC4256C-5F256BI ¹	256	1.8	5	fpBGA	256	160	I
	LC4256C-75F256BI ¹	256	1.8	7.5	fpBGA	256	160	I
	LC4256C-10F256BI ¹	256	1.8	10	fpBGA	256	160	I
	LC4256C-5T176I	256	1.8	5	TQFP	176	128	I
	LC4256C-75T176I	256	1.8	7.5	TQFP	176	128	I
	LC4256C-10T176I	256	1.8	10	TQFP	176	128	I
	LC4256C-5T100I	256	1.8	5	TQFP	100	64	I
	LC4256C-75T100I	256	1.8	7.5	TQFP	100	64	I
	LC4256C-10T100I	256	1.8	10	TQFP	100	64	I

ispMACH 4000B (2.5V) Lead-Free Industrial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4128B	LC4128B-5TN128I	128	2.5	5	Lead-Free TQFP	128	92	I
	LC4128B-75TN128I	128	2.5	7.5	Lead-Free TQFP	128	92	I
	LC4128B-10TN128I	128	2.5	10	Lead-Free TQFP	128	92	I
	LC4128B-5TN100I	128	2.5	5	Lead-Free TQFP	100	64	I
	LC4128B-75TN100I	128	2.5	7.5	Lead-Free TQFP	100	64	I
	LC4128B-10TN100I	128	2.5	10	Lead-Free TQFP	100	64	I
LC4256B	LC4256B-5FTN256AI	256	2.5	5	Lead-Free ftBGA	256	128	I
	LC4256B-75FTN256AI	256	2.5	7.5	Lead-Free ftBGA	256	128	I
	LC4256B-10FTN256AI	256	2.5	10	Lead-Free ftBGA	256	128	I
	LC4256B-5FTN256BI	256	2.5	5	Lead-Free ftBGA	256	160	I
	LC4256B-75FTN256BI	256	2.5	7.5	Lead-Free ftBGA	256	160	I
	LC4256B-10FTN256BI	256	2.5	10	Lead-Free ftBGA	256	160	I
	LC4256B-5FN256AI ¹	256	2.5	5	Lead-Free fpBGA	256	128	I
	LC4256B-75FN256AI ¹	256	2.5	7.5	Lead-Free fpBGA	256	128	I
	LC4256B-10FN256AI ¹	256	2.5	10	Lead-Free fpBGA	256	128	I
	LC4256B-5FN256BI ¹	256	2.5	5	Lead-Free fpBGA	256	160	I
	LC4256B-75FN256BI ¹	256	2.5	7.5	Lead-Free fpBGA	256	160	I
	LC4256B-10FN256BI ¹	256	2.5	10	Lead-Free fpBGA	256	160	I
	LC4256B-5TN176I	256	2.5	5	Lead-Free TQFP	176	128	I
	LC4256B-75TN176I	256	2.5	7.5	Lead-Free TQFP	176	128	I
	LC4256B-10TN176I	256	2.5	10	Lead-Free TQFP	176	128	I
	LC4256B-5TN100I	256	2.5	5	Lead-Free TQFP	100	64	I
LC4256B-75TN100I	256	2.5	7.5	Lead-Free TQFP	100	64	I	
LC4256B-10TN100I	256	2.5	10	Lead-Free TQFP	100	64	I	
LC4384B	LC4384B-5FTN256I	384	2.5	5	Lead-Free ftBGA	256	192	I
	LC4384B-75FTN256I	384	2.5	7.5	Lead-Free ftBGA	256	192	I
	LC4384B-10FTN256I	384	2.5	10	Lead-Free ftBGA	256	192	I
	LC4384B-5FN256I ¹	384	2.5	5	Lead-Free fpBGA	256	192	I
	LC4384B-75FN256I ¹	384	2.5	7.5	Lead-Free fpBGA	256	192	I
	LC4384B-10FN256I ¹	384	2.5	10	Lead-Free fpBGA	256	192	I
	LC4384B-5TN176I	384	2.5	5	Lead-Free TQFP	176	128	I
	LC4384B-75TN176I	384	2.5	7.5	Lead-Free TQFP	176	128	I
	LC4384B-10TN176I	384	2.5	10	Lead-Free TQFP	176	128	I
LC4512B	LC4512B-5FTN256I	512	2.5	5	Lead-Free ftBGA	256	208	I
	LC4512B-75FTN256I	512	2.5	7.5	Lead-Free ftBGA	256	208	I
	LC4512B-10FTN256I	512	2.5	10	Lead-Free ftBGA	256	208	I
	LC4512B-5FN256I ¹	512	2.5	5	Lead-Free fpBGA	256	208	I
	LC4512B-75FN256I ¹	512	2.5	7.5	Lead-Free fpBGA	256	208	I
	LC4512B-10FN256I ¹	512	2.5	10	Lead-Free fpBGA	256	208	I
	LC4512B-5TN176I	512	2.5	5	Lead-Free TQFP	176	128	I
	LC4512B-75TN176I	512	2.5	7.5	Lead-Free TQFP	176	128	I
LC4512B-10TN176I	512	2.5	10	Lead-Free TQFP	176	128	I	

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000V (3.3V) Lead-Free Industrial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4256V	LC4256V-5FTN256AI	256	3.3	5	Lead-free ftBGA	256	128	I
	LC4256V-75FTN256AI	256	3.3	7.5	Lead-free ftBGA	256	128	I
	LC4256V-10FTN256AI	256	3.3	10	Lead-free ftBGA	256	128	I
	LC4256V-5FTN256BI	256	3.3	5	Lead-free ftBGA	256	160	I
	LC4256V-75FTN256BI	256	3.3	7.5	Lead-free ftBGA	256	160	I
	LC4256V-10FTN256BI	256	3.3	10	Lead-free ftBGA	256	160	I
	LC4256V-5FN256AI ¹	256	3.3	5	Lead-free fpBGA	256	128	I
	LC4256V-75FN256AI ¹	256	3.3	7.5	Lead-free fpBGA	256	128	I
	LC4256V-10FN256AI ¹	256	3.3	10	Lead-free fpBGA	256	128	I
	LC4256V-5FN256BI ¹	256	3.3	5	Lead-free fpBGA	256	160	I
	LC4256V-75FN256BI ¹	256	3.3	7.5	Lead-free fpBGA	256	160	I
	LC4256V-10FN256BI ¹	256	3.3	10	Lead-free fpBGA	256	160	I
	LC4256V-5TN176I	256	3.3	5	Lead-free TQFP	176	128	I
	LC4256V-75TN176I	256	3.3	7.5	Lead-free TQFP	176	128	I
	LC4256V-10TN176I	256	3.3	10	Lead-free TQFP	176	128	I
	LC4256V-5TN144I	256	3.3	5	Lead-free TQFP	144	96	I
	LC4256V-75TN144I	256	3.3	7.5	Lead-free TQFP	144	96	I
	LC4256V-10TN144I	256	3.3	10	Lead-free TQFP	144	96	I
	LC4256V-5TN100I	256	3.3	5	Lead-free TQFP	100	64	I
	LC4256V-75TN100I	256	3.3	7.5	Lead-free TQFP	100	64	I
LC4256V-10TN100I	256	3.3	10	Lead-free TQFP	100	64	I	
LC4384V	LC4384V-5FTN256I	384	3.3	5	Lead-free ftBGA	256	192	I
	LC4384V-75FTN256I	384	3.3	7.5	Lead-free ftBGA	256	192	I
	LC4384V-10FTN256I	384	3.3	10	Lead-free ftBGA	256	192	I
	LC4384V-5FN256I ¹	384	3.3	5	Lead-free fpBGA	256	192	I
	LC4384V-75FN256I ¹	384	3.3	7.5	Lead-free fpBGA	256	192	I
	LC4384V-10FN256I ¹	384	3.3	10	Lead-free fpBGA	256	192	I
	LC4384V-5TN176I	384	3.3	5	Lead-free TQFP	176	128	I
	LC4384V-75TN176I	384	3.3	7.5	Lead-free TQFP	176	128	I
LC4384V-10TN176I	384	3.3	10	Lead-free TQFP	176	128	I	
LC4512V	LC4512V-5FTN256I	512	3.3	5	Lead-free ftBGA	256	208	I
	LC4512V-75FTN256I	512	3.3	7.5	Lead-free ftBGA	256	208	I
	LC4512V-10FTN256I	512	3.3	10	Lead-free ftBGA	256	208	I
	LC4512V-5FN256I ¹	512	3.3	5	Lead-free fpBGA	256	208	I
	LC4512V-75FN256I ¹	512	3.3	7.5	Lead-free fpBGA	256	208	I
	LC4512V-10FN256I ¹	512	3.3	10	Lead-free fpBGA	256	208	I
	LC4512V-5TN176I	512	3.3	5	Lead-free TQFP	176	128	I
	LC4512V-75TN176I	512	3.3	7.5	Lead-free TQFP	176	128	I
	LC4512V-10TN176I	512	3.3	10	Lead-free TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.